

Abstract of th Disclosure

A forming method of a resist pattern includes the following two steps. The first step is to carry out a heat treatment of a substrate, on which a resist pattern is formed, in a first heat treatment temperature in a first treatment period. The second step is to change said first heat treatment temperature to a second heat treatment temperature during said heat treatment such that a variation of dimensions of said resist pattern in said heat treatment reaches a desirable variation in a second treatment period.